

Part Number: XZCBD55W-A2RT

3.2x1.6mm SMD CHIP LED LAMP

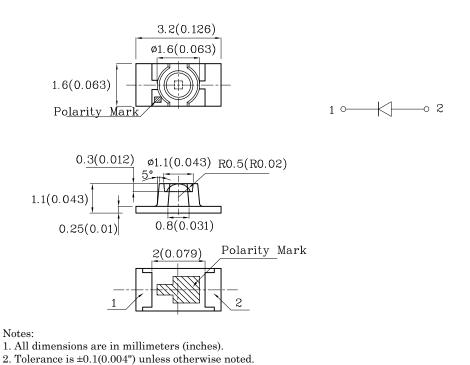
Features

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2,000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- \bullet RoHS compliant





Package Schematics



3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)	Blue (InGaN)	Unit		
Reverse Voltage	V_{R}	5	V	
Forward Current	\mathbf{I}_{F}	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	150	mA	
Power Dissipation	\mathbf{P}_{D}	120	mW	
Electrostatic Discharge Threshold (HBM)	250	V		
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C	
Storage Temperature	Tstg	-40 ~ +85	C	

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T _A =25°C)		Blue (InGaN)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	3.3	V	
Forward Voltage (Max.) (I _F =20mA)	V_{F}	4	V	
Reverse Current (Max.) (V _R =5V)	I_R	50	uA	
Wavelength of Peak Emission CIE127-2007*(Typ.) (I _F =20mA)	λP	460*	nm	
Wavelength of Dominant Emission CIE127-2007*(Typ.) $(I_F=20mA)$	λD	465*	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	25	nm	
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	100	pF	

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I _F =20mA) mcd		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZCBD55W-A2RT	Blue	InGaN	Water Clear	120*	248*	460*	80°

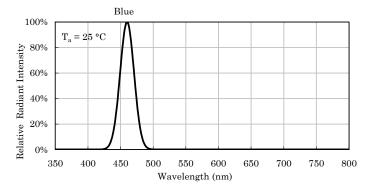
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

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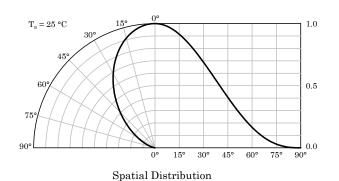
XDSB3962 V6-Z Layout: Maggie L.



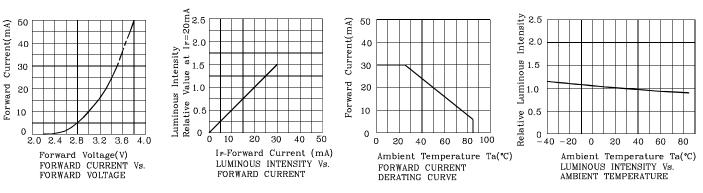
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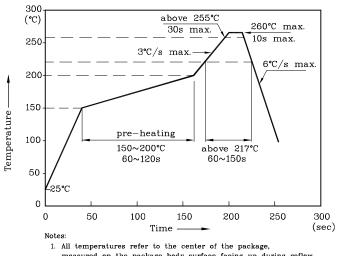
Relative Intensity Vs. CIE Wavelength







LED is recommended for reflow soldering and soldering profile is shown below.



Reflow Soldering Profile for SMD Products (Pb-Free Components)

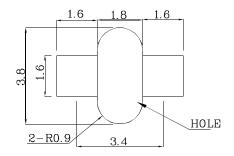
measured on the package body surface facing up during reflow

2. Do not apply any stress to the LED during high temperature conditions. 3. Maximum number of soldering passes: 2

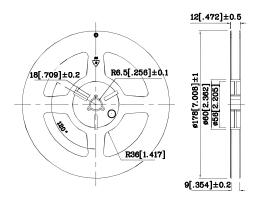


The device has a single mounting surface. The device must be mounted according to the specifications.

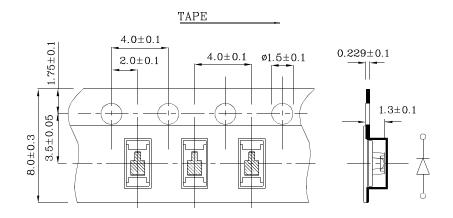
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

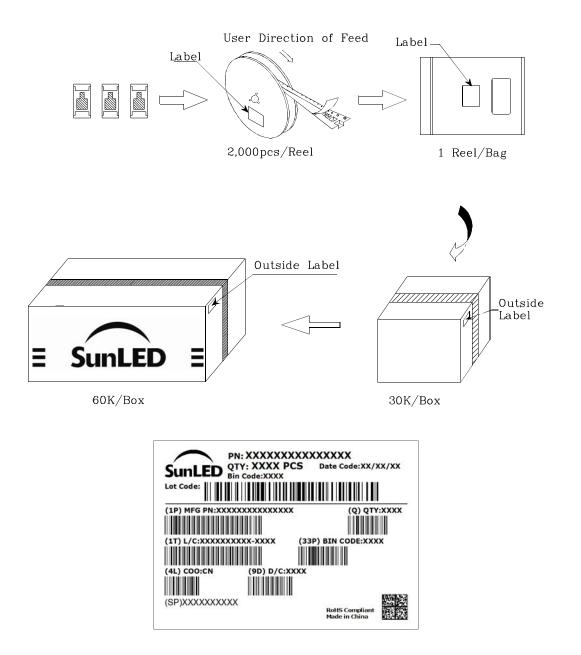
2. Luminous intensity / luminous flux: +/-15%

3. Forward Voltage: +/-0.1V $\,$

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
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- Additional technical notes are available at <u>https://www.SunLEDusa.com/TechnicalNotes.asp</u>

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